Plastic Packages for Integrated Circuits

Package Outline Drawing

W5x6.30C
5X6 ARRAY 30 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)
Rev 0, 6/14


2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.

3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.

4. Bump position designation per JESD 95-1, SPP-010.

5. There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.

NOTES: